

FEATURES

Low profile package

Idea for printed circuit board

Glass passivated Junction chip

High forward surge current capability

Meet AEC-Q101 Requirements





Schematic Symbol

MECHANICAL DATA

Rating 94V-0
Moisture Sensitivity: Level 1 per J-STD-020
Polarity: Cathode line denotes the cathode end

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

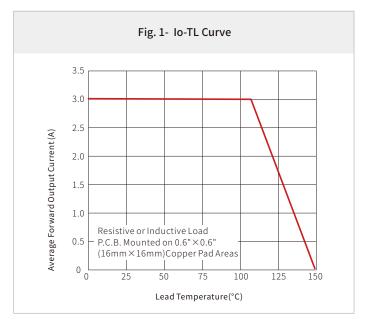
MAXIMUM RATINGS AND CHARACTERISTICS ($T_A = 25$ °C)

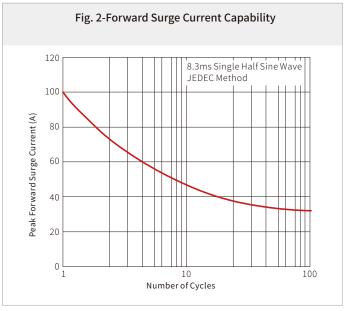
Parameter		Symbol	GS3AQ	GS3BQ	GS3DQ	GS3GQ	GS3JQ	GS3KQ	GS3MQ	Unit
Marking			GS3A	GS3B	GS3D	GS3G	GS3J	GS3K	GS3M	
Maximum repetitive peak reverse voltage		V_{RRM}	50	100	200	400	600	800	1000	
Maximum RMS voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage		V_{DC}	50	100	200	400	600	800	1000	
Average Rectified Output Current @60Hz sine wave, Resistance load, T	Average Rectified Output Current @60Hz sine wave, Resistance load, TL (FIG.1)		3.0							
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25°C Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C		I _{FSM}	100 200						А	
Maximum instantaneous forward voltage I_{FM} =3.0A		V_{F}	1.0						V	
Maximum DC reverse current at	T _J =25°C	1	5						μА	
rated DC blocking voltage	T _J =125°C	- I _R	100							
Typical junction capacitance Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C		CJ	25						рF	
Current squared time @1ms≤t≤8.3ms Tj=25°C		l²t	41.5						A ² s	
		$R_{\theta J\text{-A}}$				48				
Typical Thermal Resistance (1)	$R_{\theta J-L}$	15						°C/W		
		$R_{\theta J\text{-C}}$				12				
Operating junction and storage temperature range		T_{J},T_{STG}	-55 to +150						°C	

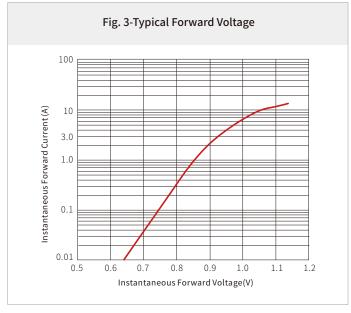
Note(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.6" \times 0.6" (16 mm \times 16 mm) copper pad areas

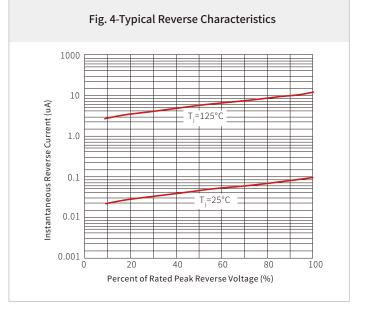


CHARACTERISTIC CURVES





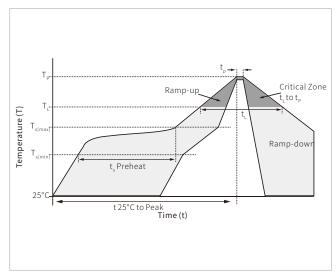




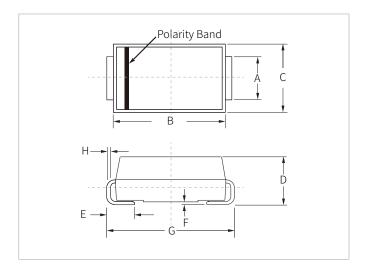


SOLDERING PARAMETERS

	Lead-free assembly			
	Temperature Max (T _{s(min)})	150°C		
Pre Heat	Temperature Max (T _{s(max)})	200°C		
	Time (min to max) (t _s)	60 – 180 secs		
Average ran	Average ramp up rate (Liquidus Temp (T_L) to peak			
	3°C/second max			
Reflow	Temperature (T _L) (Liquidus)	217°C		
Reliow	Time (min to max) (t _L)	60 – 150 seconds		
Peak Temp	260°C			
Time within	20 – 40 seconds			
Ramp-dow	6°C/second max			
Time 25°C t	8 minutes max.			
Do not exce	260°C			



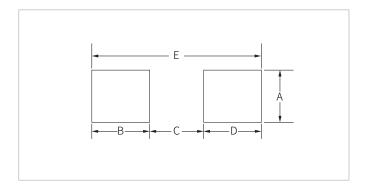
DO-214AB(SMC) PACKAGE INFORMATION



Ref.	Millin	ieters	Inches			
i.e.i.	Min.	Max.	Min.	Max.		
А	2.80	3.20	0.110	0.126		
В	6.60	7.20	0.260	0.283		
С	5.70	6.10	0.224	0.240		
D	2.15	2.75	0.085	0.108		
Е	1.00	1.60	0.039	0.063		
F	0.02	0.20	0.000	0.008		
G	7.60	8.00	0.299	0.315		
Н	0.15	0.30	0.006	0.012		



RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millim	neters	Inches			
KCI.	Min.	Max.	Min.	Max.		
А	3.30	-	0.129	-		
В	2.40	-	0.094	-		
С	-	4.20	-	0.165		
D	2.40	-	0.094	-		
Е	8.20	REF	0.323REF			

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
GS3AQ-GS3MQ	DO-214AB(SMC)	3000PCS	13"



Headquarters

No.3387 Shendu Road Pujiang I&E Park Minhang Shanghai China 201000

Hotline 400-021-5756

Web

Https://www.semiware.com

Sales Center

Tel: 86-21-3463-7458

Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001

Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654

Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172

Ext: 8868

Email: cs03@semiware.com

By QR Code





Website

Mechai

To find your local partner within Semiware's global website: www.semiware.com © 2022 Semiware Semiconductor Inc.

The content of this document has been carefully checked and understood. However, neither Semiware nor its subsidiaries assume any liability whatsoever for any errors or inaccuracies of this document and the consequences thereof. Published specifications are subject to change without notice. Product suitability for any area of application must ultimately be determined by the customer. In all cases, products must never be operated outside their published specifications. Semiware does not guarantee the availability of all published products. This disclaimer shall be governed by substantive Chinese law and resulting disputes shall be settled by the courts at the place of business of Semiware. Latest publications and a complete disclaimer can be downloaded from the Semiware website. All trademarks recognized.